

Silicon drift detectors and their application on XGIS instrument for the Theseus mission

> V. Tichý, L. Amati, C. Labanti, R. Campana in behalf of Theseus-XGIS team December 2019

Theseus (Transient High Energy Sky Early Universe Surveyor)

- ESA M5 Candidate mission
- Probing the physical properties of the early universe with high-redshift GRBs
- Multimessenger time domain astrophysics with deep monitoring of X-ray transient sky
- Broadband simultaneous NIR and X/γ-ray observations for thousands of faint X-ray sources
- Flexible follow-up observatory (ToO, guest observer program)

The X/Gamma-ray Imaging Spectrometer (XGIS) on-board THESEUS





Figure 2: THESEUS spacecraft current design and payload accommodation



Germany+PL+DK

XGIS: need, role and concept



- The SXI grants the required combination of sensitivity, FOV and location accuracy in the soft X-rays for high-z GRBs and many classes of soft X-ray transients (including e.m. counterparts of some GW signals)
- Main limitation of SXI is the soft energy band (< 5 keV) -> a broad band spectral coverage (up to several MeVs) is needed, in order to:
- ✓ improve the efficiency in classifying and filtering the SXI triggers
- detect and localize any kind of GRBs including short ones (fundamental for multi-messenger astrophysics)
- ✓ getting clues to the emission physics and progenitors of GRBs and other transients

Theseus Payload

- Soft X-ray Imager (SXI) a set of four Lobster-Eye telescopes
 - 0.3–5 keV band (CMOS detector), $\sim 2 \cdot 10^{-10}$ erg cm⁻² s⁻¹ sensitivity
 - 1 sr FoV
 - Source Localisation Accuracy of \sim 1'.
- X-Gamma Imaging Spectrometer (XGIS) a set of two X-γ cameras
 - 2 keV 10 MeV band (imaging up to 150keV)
 - 2.5 sr FoV (overlapping SXI)
 - Source Localisation Accuracy of \sim 5'.
- InfraRed Telescope (IRT) 70 cm IR Korsch telescope
 - 0.7–1.8 μm
 - 10'x10' FoV
 - Imaging and (moderate) spectroscopy (low res. default, high res. for bright sources).



XGIS X-Gamma ray Imaging Spectrometer





- 2 units
- imaging in 2-150 keV
- detection up to ca. 10MeV
- FoV 77°x77° per unit
- Total FoV 77°x117° (37° overlap)



XGIS structure









Mask assembly

Mask: 1mm thick tungsten

Collimator assembly

Collimator: 0.25 mm thick tungsten

Detector assembly

+ Data handling unit (DHU)

+ Power supply unit (PSU)

Overall dimension of the mask an collimator

External dimension of the mask plane 600x600 mm to give room for a flange connecting the plane to the collimator



Why to use silicon drift detectors (SDD)



- low noise
- good energy resolution
- well proved technology
- can be made of defferent sizes and areas including a big volume
- can be used for detection of wide spectrum of EM radiation
- can be used with a scintillator



Operating principle of a Silicon Drift Detector





Silicon Drift Detectors at FBK-Tn



Silicon Drift Detectors (SDD) from REDSOX project (INFN) realized at Fondazione Bruno Kessler (FBK Trento)



Orion ASIC readout



Si PIN vs SDD



1998 – 2003

Noise performance of the Si PIN PD used in INTEGRAL PICsIT (area PD 1 cm²) and AGILE MCAL (area PD 3.5 cm²)

Si directly illuminated with an ²⁴¹Am source (X lines @ 14.0, 17.7, 59.6 keV)

Noise ~ 1000 e⁻ rms @ 20 °C Power ~ 10 mW



2016

Noise performance of the **SDD PD** Produced in FBK (area PD 1 cm²)

Si directly illuminated with an ²⁴¹Am source (X lines @ 14.0, 17.7, 59.6 keV)

VEGAASIC Noise ~ 15 e rms @ 20 °C Power ~ 0.5 mW

SIRIO ASIC Noise ~ 8 e⁻ rms @ 20 °C Power ~ 8 mW



Module structure





- Detection band 2keV-
- Top and bottom PCB contain preamplifiers
- CsI(TI) scintillator 4.5x4.5x30 mm
- PCB with Logic distinguish between X-ray and gamma



SDD

Ancora un altro design

CsI (TI) scintillator

Scintillator bar with double-SDD readout

Dual architecture

X-ray events: direct absorption and readout by SDD-A (Theseus only)



SDD

γ-ray events: scintillation light readout by both SDDs Position reconstruction possible using the two signals

Orion FE & BE Proposed architecture for pixel readout





- 2 shaping times, faster for X and slower for Y events (3 amps total)
- 2 discriminators for X and Y events
- Individual ADC for each amp line (3 ADC total)
- Event data formation inside the channel with logic for selection between X and Y event
- Timing of the event loaded from an external 'Time bus' at the occurence of the event

Detector assembly structure



